



Final Product Change Notification

201206025F02

Issue Date: 14-Sep-2013

Effective Date: 15-Oct-2013

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QUALITY

Management Summary

Introduction of CuPd coated wire bonding for TSSOP28 package for TDA8024TT/C1 product at Amkor (ATP).
New 12NC has been created (see below).

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Cu Wire introduction for TDA8024TT at Amkor

Details of this Change

Introduction of CuPd coated wire bonding for TSSOP28 package for TDA8024TT/C1 product at ATP (Amkor Philippines).

APB is qualified with Cu wire bonding already.

New Sales Item TDA8024TT/C1/S1 (12NC 9352 991 52118) has been created.

Why do we Implement this Change

Standardization of assembly process, aligning with world trend technology.

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Samples are available from 23-Sep-2013

Production

Planned first shipment 04-Nov-2013

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information
Self qualification _____

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Oct-2013.

Remarks

APB is qualified with Cu wire bonding already.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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